Compliant with IEC 62474/ D9.00

Compliant to IEC 61249-2-21:2003

MICROCHIP Semiconductor Device Type: H7A 006 VDFN 3.2x5.0x0.9mm NiPdAu				Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials			
		"Contained In"	% Total			18.86	(mg) Total	Mold Compound	% ot Total Weight	e3 46.57
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm		, ,,			1
Silica, vitreous (or fused)	60676-86-0	Mold Compound	39.585	16.032	395,845		Silica, vitreous (or fused)	60676-86-0	85.00	
Epoxy Resin Phenolic Resin	Trade Secret Trade Secret	Mold Compound Mold Compound	3.958 1.630	1.603 0.660	39,585 16,300		Epoxy Resin Phenolic Resin	Trade Secret Trade Secret	8.50 3.50	
Silica, vitreous (or fused)	7631-86-9	Mold Compound	1.257	0.509	12,574		Silica, vitreous (or fused)	7631-86-9	2.70	
Carbon Black	1333-86-4	Mold Compound	0.140	0.057	1,397		Carbon Black	1333-86-4	0.30	-
Copper	7440-50-8	Lead Frame	45.079	18.257	450,791		Carbon black	Total	100.00	4
Iron	7439-89-6	Lead Frame	1.066	0.432	10,656	18.76	(mg) Total	Lead Frame	% of Total Weight	46.33
Zinc (Metal)	7440-66-0	Lead Frame	0.116	0.047	1,158		Copper	7440-50-8	97.30	
Phosphorous Silica Franci	7723-14-0	Lead Frame	0.069	0.028	695		Iron	7439-89-6 7440-66-0	2.30 0.25	-
Silica Fused Epoxy Resin	60676-86-0 120206-26-0	Die Attach 1 Die Attach 1	0.388 0.115	0.157 0.046	3,879 1,148		Zinc (Metal) Phosphorous	7440-66-0	0.25	-
Poly(Bisphenol A-co-epichlorohydrin)	25068-38-6	Die Attach 1	0.087	0.035	874		1 Hoophorodo	Total	100.00	1
Silver	7440-22-4	Die Attach 2	0.367	0.148	3,666	0.24	(mg) Total	Die Attach 1	% of Total Weight	0.59
Acrylic Resin	Trade secret	Die Attach 2	0.103	0.042	1,034		Silica Fused	60676-86-0	65.74	
Doped Silicon	7440-21-3	Chip (Die) 1	2.590	1.049	25,900		Epoxy Resin	120206-26-0	19.45	
Doped Silicon	7440-21-3	Chip (Die) 2	1.580	0.640	15,800		Poly(Bisphenol A-co- epichlorohydrin)	25068-38-6	14.81	
Doped Gold	7440-57-5	Wire Bond 1	0.360	0.146	3.600		epiciliororiyaliri)	Total	100.00	1
Doped Gold	7440-57-5	Wire Bond 2	0.150	0.061	1,500	0.19	(mg) Total	Die Attach 2	% of Total Weight	
Nickel	7440-02-0	Plating on external leads (pins)	1.281	0.519	12,814		Silver	7440-22-4	78.00	
Palladium	7440-05-3	Plating on external leads (pins)	0.049	0.020	491		Acrylic Resin	Trade secret	22.00	
Gold	7440-57-5	Plating on external leads (pins)	0.030	0.012	295			Total	100.00	
		TOTALS:	100.000	40.500	1,000,000	1.05	Total (mg)	Chip (Die) 1	% of Total Weight	2.59
		g Total Mass	100.000	40.300	1,000,000	1.03	Doped Silicon	7440-21-3	100	7 2.39
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pliance with the above EU Directives has been verified via inter hemical substance is absent from the list above, the chemical rporated's knowledge and belief as of the date of this documer	rnal design contro substance is NOT t, there is no credi	ls, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor devic ible reason to believe that the unavoidable impurity	e and, to the best o	of Microchip Te	chnology	0.64	Total (mg) Doped Silicon	Total Chip (Die) 2 7440-21-3	% of Total Weight	
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5) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption ppliance with the above EU Directives has been verified via interchemical substance is absent from the list above, the chemical proprated's knowledge and belief as of the date of this documer below the threshold of regulatory concern for any regulatory so ding compounds used by Microchip meet the UL94 V0 flammab ://lul.com/global/eng/pages/offerings/industries/chemicals/plast protective "tubes" in which the specific product is shipped are ain "reels" may be made from PVC plastic. Trochip Technology Incorporated believes the information in this roriginal packing materials is true and correct to the best of its upleteness and accuracy of data in this form because it has been mation is often protected from disclosure as trade secrets and ridded only as estimates of the average weight of these parts and ants, metals, and non-metal materials contained within silicon crochip Technology Incorporated does not provide any warranty ranties provided by Microchip Technology Incorporated and its tations, sales order acknowledgement, and invoices. Trochip disclaims any duty to notify users of updates or changes ered by users or third parties as a result of the users' reliance of embled package referenced above is EU REACH compliant base of the second of the se	mal design contro substance is NOT t, there is no credi heme world-wide. Ility standard for p ics/ made from polyvi form concerning knowledge and be n compiled based some information the average weig levices (silicon IC) express or implie subsidiaries are c to Material Conte n the information	is, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device the reason to believe that the unavoidable impurity is lastics. You can access the UL iQTM family of databinyl chloride (PVC) plastic. "Window envelopes" user substances restricted by RoHS in Microchip Technolief, as of the date listed in this form. Microchip Technon the ranges provided in Material Safety Data Sheet may not have been provided by subcontract assemblet of anticipated significant toxic metals component in the finished parts. d, with respect to the information provided in this donatained in Microchip's standard terms and condition to Declarations and shall not be liable for any damagin Material Content Declarations (MCD) or independe	e and, to the best o concentration of the asses to obtain a tes to hold the packin logy Incorporated's provided by raw relers and raw mater s. These estimates of sale. These arees, direct or indirected and record in the content of	of Microchip Te e chemical sub: treport at ug slip on the o s semiconductor ed cannot guar naterial suppliers. Ir do not include usive, limited pre provided in I	chnology stance, if any, is uter box and or devices in rantee the ers. Supplier nformation is trace levels of oroduct Microchip's ial or otherwise,	0.15	Doped Silicon (mg) Total Doped Gold (mg) Total Doped Gold (mg) Total Nickel Palladium	Chip (Die) 2 7440-21-3 Total Wire Bond 1 7440-57-5 Total Wire Bond 2 7440-57-5 Total Plating on external leads (pins) 7440-02-0 7440-05-3	% of Total Weight 100 100.00 % of Total Weight 100.00 % of Total Weight 100 100.00 % of Total Weight 94.22 3.61	0.36

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